REMARKS

Claim 20 is pending in the present application. No amendment has been proposed. It is respectfully submitted that this Amendment is fully responsive to the Office Action dated June 15, 2005.

Information Disclosure Statement:

It is respectfully submitted that the Examiner has failed to consider the IDS filed on June 6, 2005 by the Applicants. As such, it is requested that the Examiner properly consider such IDS and provide Applicants with an initialed copy of the accompanied PTO Form-1449 filed with the IDS on June 6, 2005.

As to the Merits:

As to the merits of this case, the Examiner relies on the new cited reference of Hembree et al. (U.S. Patent No. 6,060,891) in setting forth the following rejection:

Claim 20 stands rejected under 35 USC 102(b) as being anticipated by Hembree et al.

This rejection is respectfully traversed.

Claim 20 calls for *electrically connecting electrode pads of a device testing contactor to electrodes of a device being tested; the electrode pads being formed on a membrane-type flexible wiring board of the device testing contactor, and being reinforced by a reinforcing member, and*

the device testing contactor comprising the wiring board and the reinforcing member collectively molded and bonded to each other.

According to the Examiner's comments in the Action, Hembree discloses in figures 4 and 5 and col. 6, lines 50-52 and lines 57-68, a method of testing a device comprising the step of electrically connecting electrode pads (contact member 20) of a device testing contactor (probe card 10) to electrodes (contact locations 15) of a device being tested (semiconductor dice 14); the electrode pads (contact member 20) being formed on a membrane-type flexible wiring board (16) of the device testing contactor (probe card 10), and being reinforced by a reinforcing member (compressible member 28), and the device testing contactor (probe card 10) comprising the wiring board (16) and the reinforcing member (28) collectively molded and bonded to each other.

However, the device testing contactor (probe card 10) taught by Hembree comprises an interconnect substrate 16 and a membrane 18. The interconnect substrate 16 includes patterns of contact members 20 configured to electrically contact the contact locations 15 (figure 4) on the semiconductor dice 14. The membrane 18 physically and electrically attaches the interconnect substrate 16 to a probe card fixture 22 mounted to the testing apparatus (col. 6, lines 5-11).

Clearly, Hembree does not disclose o r suggest the applicants' claimed "membrane-type flexible wiring board of the device testing contactor". The interconnect substrate 16 of Hembree is not membrane-type flexible wiring board.

Moreover, Hembree does not disclose or suggest the device testing contactor (probe card 10) comprising the wiring board (16) and the reinforcing member (28) collectively molded and bonded to each other, as in the applicants' invention (current claim 20).

According to Hembree (col. 6, line 65 to col. 7 line 1), the compressible member 28 can be secured to the interconnect substrate 16 and pressure plate 30 using an adhesive such as silicone. Clearly, according to the teaching of Hembree, the wiring board (16) and the reinforcing member (28) are not collectively molded and bonded.

In contrast to the teaching of Hembree, the applicants disclose that the first reinforcing member 12A bonded to the rear surface of the wiring board 11 is collectively molded with the wiring board as disclosed on pages 7-8 in the specification. The wiring board 11A of the applicants' invention is a membrane-type wiring board with, flexibility as disclosed on page 7, lines 24-25 in the Specification.

For at least the above-mentioned reasons, it is submitted that Hembree clearly does not disclose or suggest the applicant's claimed device testing method of claim 20 concerning *the electrode pads being formed on a membrane-type flexible wiring board of the device testing contactor, and being reinforced by a reinforcing member, and the device testing contactor comprising the wiring board and the reinforcing member collectively molded and bonded to each other.* As such, it is respectfully requested that the Examiner reconsider the case in view of the above arguments and withdraws the rejection from the application.

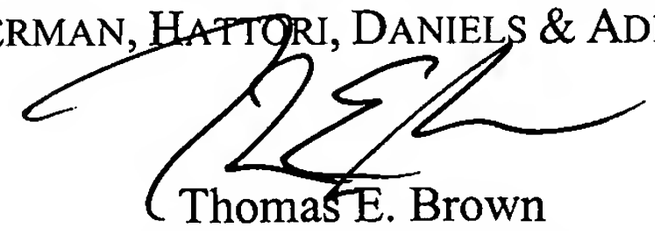
In view of the aforementioned remarks, Applicants submit that that the claims are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP



Thomas E. Brown
Attorney for Applicants
Registration No. 44,450
Telephone: (202) 822-1100
Facsimile: (202) 822-1111

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